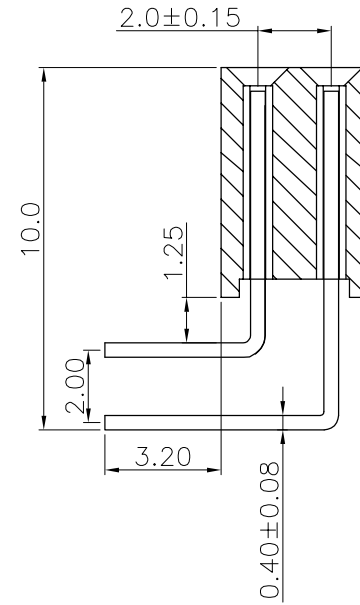
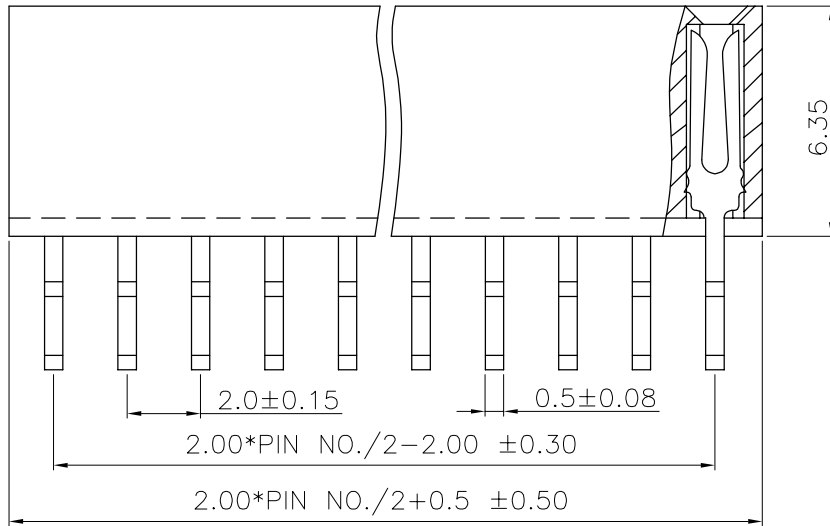
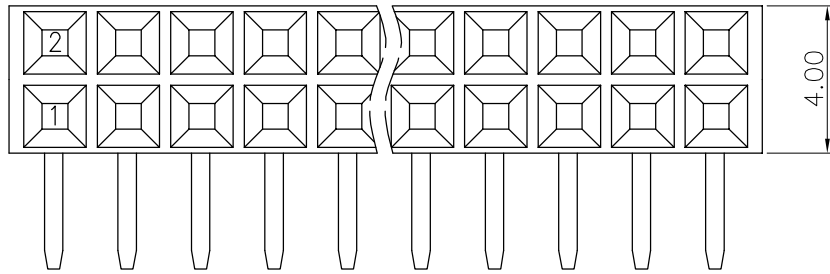
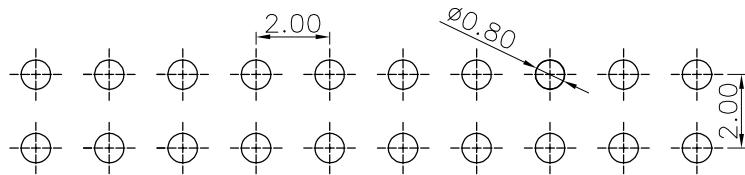


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements



NOTE:
 1.MATERIAL SPECIFICATION:
 1-1.HOUSING: THERMOPLASTIC HIGH TEMP,UL94V-0
 1-2.CONTACTS: BRASS
 2.PLATING SPECIFICATION:
 2-1.CONTACTS:
 GOLD FLASH OVER NICKEL
 3.ELECTRICAL PERFORMANCE:
 3-1.CURRENT RATING: 2A
 3-2.CONTACT RESISTANCE: 30 mΩ MAX
 3-3.INSULATION RESISTANCE: 1000MΩ Min
 3-4.DIELECTRIC WITHSTANDING : 300V
 4.ENVIRONMENTAL PERFORMANCE:
 4-1.OPERATING TEMPERATURE: -40°C~+105°C.
 5.PACKAGE SPEC: TRAY
 6.P/N:

FH2005 64 F 9-2 XX 1 X X X 04
 SERIES NO: _____ HOUSING: 1-PA9T
 HEIGHT: _____ COLOR: A-BLACK
 64: 6.35mm
 MALE FEMALE: _____ PLATING: A-ALL AU G/F
 F-FEMALE
 ANGLE: _____ PLATING:
 9-90° A-ALL AU G/F
 ROW NO: _____
 2-DOUBLE ROW
 PIN Q'PY: _____ TERMIPOINT:
 04~80 1-DIP



RECOMMENDED PCB LAYOUT
 (GENERAL TOLERANCE:±0.05)

REV.	REVISION RECORD	DATE	UNIT:mm	GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	
AO	NEW RELEASE	21.10.15		LINEAR	ANGLES	APPROVED	Wang_jr	21.10.15	FH200564F9-2XX1XXX04	ENDE05	
			0.00±0.25	X'±3'	DESIGNER	Gao_Han	21.10.15	TITLE:		REV: A0	SHEET: 1/1
			SIZE: A4	0.000±0.10	X'X' ±2'	DRAWN	Gao_Han	21.10.15	Pitch 2.00mm 90° 双排 DIP Y型排母 H6.35 W4.0 PC3.2		